



TESSERA 3.3-018

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of  
KHANDROS et al.

Serial No. 08/030,194

Filed: April 28, 1993

For: SEMICONDUCTOR CHIP ASSEMBLIES,  
METHODS OF MAKING SAME AND  
COMPONENTS FOR SAME

Group Art Unit: 2503

Examiner: S. Clark

Dated: June 26, 1995

Assistant Commissioner For Patents  
Washington, D.C. 20231

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GROUP 2500

AMENDMENT AND RESPONSE

Sir:

Please amend the above-identified application as follows:

In the Specification:

In the cross-reference to related applications at page 1, line 3, after  
"September 24, 1991" insert --now U.S. Pat. No. 5,347,159.--

In the Claims:

Amend Claims 1-6 as follows:

1. A semiconductor ~~chip comprising~~ <sup>assembly comprising</sup> assembly of the type including] a semiconductor chip having a plurality of surfaces and having contacts on at least one of said surfaces and a flexible sheetlike element having terminals thereon, and flexible leads electrically [connected] connecting said terminals to said contacts, [characterized in that] wherein said sheetlike element and at least some of said terminals overlie one said surface of said chip and said sheetlike element bears upon such surface of said chip, said terminals are movable with respect to said chip and said contacts; said flexible leads and said flexible sheetlike element being adapted to deform to accommodate movement of said terminals with respect to said

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on June 26, 1995.

(Signature)

MARCUS J. MILLET

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